

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 and 2 (Canceled).

3. (Currently amended) The disk enclosure of claim [[2]] 5, wherein the first plurality of elements includes at least one of a first temperature sensor, a first memory, and a first backplane controller.
4. (Currently amended) The disk enclosure of claim 3, wherein the backplane controller is coupled to a first port bypass circuit, the first port bypass circuit operable to bypass a first disk drive.
5. (Currently amended) A disk enclosure comprising:

a first enclosure controller coupled to first and second buses;

a first plurality of elements coupled to the first bus;

a first voltage circuit powering the first enclosure controller and the first plurality of elements in a first power domain;

a second enclosure controller coupled to third and fourth buses;

a second plurality of elements coupled to the fourth bus;

a second voltage circuit powering the second enclosure controller and the second plurality of elements in a second power domain;

a first switch coupled between the first and the third buses, the first switch operable to de-couple the first and the third buses when the voltage output from the second voltage circuit falls below a predetermined threshold; and

The disk enclosure of claim 3, wherein:

the first controller is coupled to a third bus;

~~the second controller is coupled to a fourth bus;~~

a second switch coupled between ~~the third and the fourth~~ ~~the second and the fourth~~ buses, the second switch operable to de-couple ~~the third and the fourth~~ ~~the second and the fourth~~ buses when the voltage output from the first voltage circuit falls below [[a]] the predetermined threshold.

Claim 6 (Canceled).

7. (Currently amended) The disk enclosure of claim [[6]] 4, wherein the second plurality of elements includes at least one of a second temperature sensor, a second memory, and a second backplane controller.

8. (Currently amended) The disk enclosure of claim 7, wherein the second backplane controller is coupled to a second port bypass circuit, the second port bypass circuit operable to bypass a second disk drive.

9. (Currently amended) The disk enclosure of claim [[7]] 5, wherein:

the first enclosure controller is coupled to a fifth bus;

the second enclosure controller is further coupled to a sixth bus;

a third switch coupled between the fifth bus and a seventh bus, the third switch operable to de-couple the fifth and the seventh buses when the voltage output from the first voltage circuit falls below [[a]] the predetermined threshold; and

a fourth switch coupled between the sixth bus and the seventh bus, the fourth switch operable to de-couple the sixth and seventh buses when the voltage output from the second voltage circuit falls below [[a]] the predetermined threshold.

10. (Original) The disk enclosure of claim 9, wherein the seventh bus is further coupled to a third plurality of elements.

11. (Previously presented) The disk enclosure of claim 10, wherein the third plurality of elements includes at least one of a third temperature sensor, a third memory, a third backplane controller, and an I/O expander.

12. (Original) The disk enclosure of claim 11, wherein the I/O expander is coupled to at least one battery.

13. (Original) The disk enclosure of claim 11, wherein the I/O expander is coupled to at least one power supply.

14. (Currently amended) A disk enclosure comprising:

a first enclosure controller powered by a first voltage circuit and coupled to a first bus;

a second enclosure controller powered by a second voltage circuit and coupled to a second bus;

a first switch coupled between the first bus and a third bus, the first switch operable to de-couple the first and the third buses when the voltage output from the first voltage circuit falls below a predetermined threshold; and

a second switch coupled between the second bus and the third bus, the second switch operable to de-couple the second and the third buses when the voltage output from the first voltage circuit falls below [[a]] the predetermined threshold.

15. (Previously presented) The disk enclosure of claim 14, wherein the third bus is coupled to a first plurality of elements.

16. (Original) The disk enclosure of claim 15, wherein the first plurality of elements includes at least one of a temperature sensor, a memory, a backplane controller, and an I/O expander.

17. (Original) The disk enclosure of claim 16, wherein the I/O expander is coupled to at least one battery.

18. (Original) The disk enclosure of claim 16, wherein the I/O expander is coupled to at least one power supply.

19. (Currently amended) The disk enclosure of claim 15, wherein:

the first enclosure controller is coupled to a fourth bus;

the second enclosure controller is coupled to a fifth bus; and

a third switch coupled between the fourth and the fifth buses, the third switch operable to de-couple the fourth and the fifth buses when the voltage output from the second voltage circuit falls below a predetermined threshold.

20. (Original) The disk enclosure of claim 19, wherein the fourth bus is coupled to a second plurality of elements.

21. (Original) The disk enclosure of claim 20, wherein the second plurality of elements includes at least one of a temperature sensor, a memory, and a backplane controller.

22. (Original) The disk enclosure of claim 21, wherein the backplane controller is coupled to a port bypass circuit, the port bypass circuit operable to bypass a disk drive.

23. (Currently amended) The disk enclosure of claim 20, wherein:

the first enclosure controller is coupled to a sixth bus;

the second enclosure controller is coupled to a seventh bus; and

a fourth switch coupled between the sixth and the seventh buses, the fourth switch operable to de-couple the sixth and seventh buses when the voltage output from the first voltage circuit falls below a predetermined threshold.

24. (Original) The disk enclosure of claim 23, wherein the seventh bus is coupled to a third plurality of elements.

25. (Original) The disk enclosure of claim 24, wherein the third plurality of elements includes at least one of a temperature sensor, a memory, and a backplane controller.

26. (Original) The disk enclosure of claim 25, wherein the backplane controller is coupled to a port bypass circuit, the port bypass circuit operable to bypass a disk drive.

27. (Previously presented) The disk enclosure of claim 1, wherein the first and the second buses comprise I2C buses.

28. (Previously presented) The disk enclosure of claim 14, wherein the first, the second, and the third buses comprise I2C buses.